

L Number	Hits	Search Text	DB	Time stamp
2	1	("6627466").PN.	USPAT	2004/01/19 11:06
3	195	(wafer with fabrication) and apparatus and (wafer with handling) and sensor and contaminant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/19 11:06
4	36	(wafer with fabrication) and apparatus and (wafer with handling) and sensor and contaminant and backside	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/19 11:09
5	3	(wafer with fabrication) and apparatus and (wafer with handling) and (sensor with contaminant) and backside	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/19 11:09
-	6	(wafer adj handle\$) and contaminant and backside and capacitance	USPAT	2004/01/19 11:02
-	1	(wafer) and (detect with contaminant) and backside	USPAT	2003/04/16 13:46
-	1	"5780204".PN.	USPAT	2003/04/16 13:45
-	1	"5710624".PN.	USPAT	2003/04/16 13:45
-	383	wafer adj handler	USPAT	2003/04/16 13:46
-	6	((wafer adj handler) and contaminant) and backside	USPAT	2003/04/16 13:46
-	33	(wafer adj handler) and contaminant	USPAT	2003/04/16 13:48
-	3	(wafer adj handler) and contaminant and capacitance	USPAT	2003/04/16 13:50
-	806	(438/14).CCLS.	USPAT	2003/04/16 13:50
-	24	((438/14).CCLS.) and (handler or carrier) and backside	USPAT	2003/04/16 13:51
-	5	((438/14).CCLS.) and (handler or carrier) and backside and (contaminant or defect)	USPAT	2003/04/16 13:53
-	1	((438/14).CCLS.) and backside and (change with capacitance)	USPAT	2003/04/16 14:03
-	0	(detect adj defect) and (wafer with backside) and contaminant and (dielectric adj film)	USPAT	2003/04/16 14:04
-	0	(detect adj defect) and (wafer with backside) and contaminant	USPAT	2003/04/16 14:04
-	0	(detect adj defect) and (wafer with backside) and capacitance	USPAT	2003/04/16 14:04
-	2	wafer and (liquid adj crystal) and (pressure with sensing) and detect and backside	USPAT	2003/04/16 14:09
-	1	wafer and (defect or contaminant) and (sense with pressure with film)	USPAT	2003/04/16 14:55